

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|--|---|------------------|---------|------------------|
| S2 | 2 | ("6635157" "6258220").pn. | USPAT | OR | ON | 2006/03/16 18:34 |
| S3 | 72 | ("4296672" "5287237" "5435903" "5482680" "5486264" "5516418" "5597460" "5643456" "5705050" "5714521" "5785833" "5820581" "5883762" "5980706" "6022484" "6027631" "6080291" "6214193" "6270635" "6347837" "6352263" "6395101" "6423642" "6436267" "6565729" "6569297" "6635157").PN. ("20020074233" "5224504" "5489 341" "5573023" "5620581" "5731 678" "5744019" "5837120" "5996 241" "6014817" "6099702" "6099 712" "6126798" "6132857" "6136 163" "6156167" "6179983" "6228 231" "6228232" "6248222" "6254 742" "6261433" "6267853" "6273 110" "6280582" "6322674" "6322 678" "6368475" "6374837" "6383 352" "6391166" "6395152" "6409 892" "6432821" "6436249" "6440 295" "6527920" "6551487" "6569 299" "6589401").PN. ("4466864" "6113759" "6251251").PN. ("5883017").PN. ("2882209").PN. | US-PGPUB; USPAT | OR | ON | 2006/03/16 18:35 |
| S4 | 199 | (electroplating electrochemical adj plating) and (membrane diaphragm) with hydrophilic | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/17 08:56 |
| S5 | 17 | (electroplating electrochemical adj plating) and (membrane diaphragm) with hydrophilic with (polypropylene polyethylene ryton teflon) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/17 10:03 |
| S6 | 19543 | hydrophilic with (polypropylene polyethylene ryton teflon) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/17 09:04 |

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|-----|------|---|---|----|----|------------------|
| S7 | 5647 | hydrophilic near3 (polypropylene polyethylene ryton teflon) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/17 09:04 |
| S8 | 91 | S7 and ("204" "205").clas. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/17 09:04 |
| S9 | 1 | 10/690033 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/17 10:01 |
| S10 | 710 | (electroplating electrochemical adj plating) and (diffuser flow adj (adjuster distributor)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/17 10:08 |
| S12 | 272 | S10 and ("204" "205").clas. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/17 10:15 |
| S13 | 235 | S10 and ("204" "205").clas. and (wafer semiconductor microelectronics workpiece) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/03/17 10:16 |

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|-----|----|--|--------------------|----|----|------------------|
| S14 | 72 | ("4296672" "5287237" "5435903" "5482680" "5486264" "5516418" "5597460" "5643456" "5705050" "5714521" "5785833" "5820581" "5883762" "5980706" "6022484" "6027631" "6080291" "6214193" "6270635" "6347837" "6352263" "6395101" "6423642" "6436267" "6565729" "6569297" "6635157").PN. ("20020074233" "5224504" "5489 341" "5573023" "5620581" "5731 678" "5744019" "5837120" "5996 241" "6014817" "6099702" "6099 712" "6126798" "6132857" "6136 163" "6156167" "6179983" "6228 231" "6228232" "6248222" "6254 742" "6261433" "6267853" "6273 110" "6280582" "6322674" "6322 678" "6368475" "6374837" "6383 352" "6391166" "6395152" "6409 892" "6432821" "6436249" "6440 295" "6527920" "6551487" "6569 299" "6589401").PN. ("4466864" "6113759" "6251251").PN. ("5883017").PN. ("2882209").PN. | US-PGPUB; USPAT | OR | ON | 2006/03/17 10:19 |
| S15 | 28 | S14 and (diffus\$4 flow adj (adjuster distributor)) | US-PGPUB; USPAT | OR | ON | 2006/03/17 10:19 |